imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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"NASBIS" Insulating Sheet

Type: **EYGY/EYGN**

"NASBIS" is a heat insulating sheet, which is composed of silica aerogel and fiber sheet, created through impregnation process. Pore size of silica aerogel is 10 to 60nm, which means it has smaller space than the mean free path of the air, 68nm. Air molecules do not collide against each other inside the pores, and thus the component shows excellecnt heat insulation performace.

Furthermore, combining NASBIS and PGS Graphite Sheet enables controlling the direction of heat. Composite type provides greater heat insulating performance.

Features

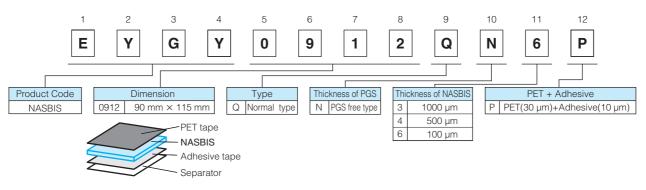
- Low thermal conductivity : 0.020 W/m · K typ.
- Created thin-film sheet ; Thickness : 100 µm to 1000 µm
- Various proposals are available when combined with PGS Graphite sheet
- RoHS compliant

Recommended applications

Smartphone, Wearable equipment, Digital Still Camera, Notebook PCs, Tablet PCs

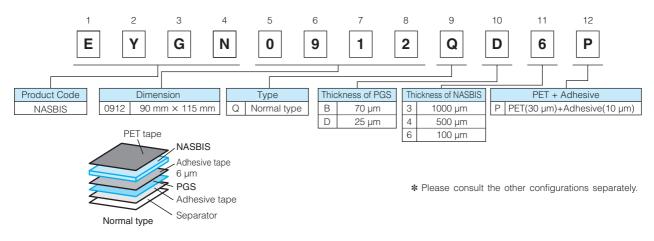
Explanation of Part Numbers

NASBIS Pouch Type (EYGY********)



* Please consult the other configurations separately.

NASBIS and PGS Composit Type (EYGN********)



Design and specifications are each subject to change without notice. Ask factory for the current technical specifications before purchase and/or use. Should a safety concern arise regarding this product, please be sure to contact us immediately. 02

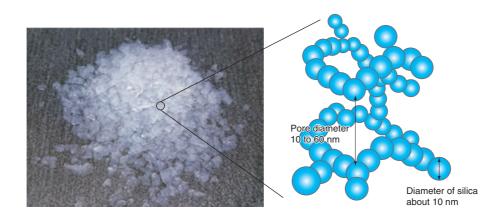
Panasonic

"NASBIS" Insulating Sheet

Characteristics of NASBIS			
Thickness	100 µm	500 µm	1000 µm
Thermal conductivity (W/(m·K))	0.018 to 0.026	0.018 to 0.026	0.018 to 0.026
Operating temperature limit (°C)	-20 to 100	-20 to 100	-20 to 100
Size / Laminate pouch (mm)	90 × 115	90 × 115	90 × 115
Heatproof temperature(°C)	100	100	100

Typical values, not guaranteed.

Appearance of silica aerogel and its nanostructure



Composition example	

NASBIS Pouch Type					
Туре		Y - P type			
Structure		PET 30 μm NASBIS* Adhesive 10 μm			
Heatproof temperature		100 °C			
100 µm*	Part No.	EYGY0912QN6P			
	Thickness (µm)	140			
500 µm*	Part No.	EYGY0912QN4P			
	Thickness (µm)	540			
1000*	Part No.	EYGY0912QN3P			
1000 µm*	Thickness (µm)	1040			

NASBIS and PGS Composit Type Normal type

-	Type N - P type		N - P type	
Structure		PET 30 μm NASBIS* Adhesive 6 μm PGS 70 μm Adhesive 10 μm	PET 30 μm NASBIS* Adhesive 6 μm PGS 25 μm Adhesive 10 μm	
Heatproof temperature		100 °C	100 °C	
100 µm* -	Part No.	EYGN0912QB6P	EYGN0912QD6P	
	Thickness (µm)	216	171	
500 µm* ·	Part No.	EYGN0912QB4P	EYGN0912QD4P	
	Thickness (µm)	616	571	
1000 µm* -	Part No.	EYGN0912QB3P	EYGN0912QD3P	
	Thickness (µm)	1116	1071	

 Above listed Part No. are examples for evaluation and selection, not for mass production. Customized service available for mass production spec.

Minimum order 10 pcs.